

### **General Description**

The MAX3158 is a high CMRR RS-485/RS-422 data-communications interface providing ±60V isolation in a hybrid microcircuit. A single +5V supply on the logic side powers both sides of the interface, with external 100V capacitors transferring power from the logic side to the isolated side. Each MAX3158 contains one transmitter and one receiver and is guaranteed to operate at data rates up to 250kbps. Drivers are short-circuit current limited and protected against excessive power dissipation by thermal shutdown circuitry that places the driver outputs into a high-impedance state. The receiver input has a fail-safe feature that guarantees a logic-high receiver output if the inputs are open, shorted, or connected to a terminated transmission line with all drivers disabled.

The MAX3158 typically draws 25mA of supply current when unloaded or when fully loaded with the driver disabled. Supply current drops to 25µA when the device is placed in shutdown mode. The device is pin selectable between half- and full-duplex mode and also features an independently programmable receiver and transmitter output phase through separate pins. The MAX3158 is a low-cost replacement for opto-isolated transceivers. For fully isolated RS-485/RS-422 transceivers, refer to the MAX1480 family data sheet.

### **Applications**

Industrial Controls Level Translators

**Telecommunications** Local Area Networks

#### Features

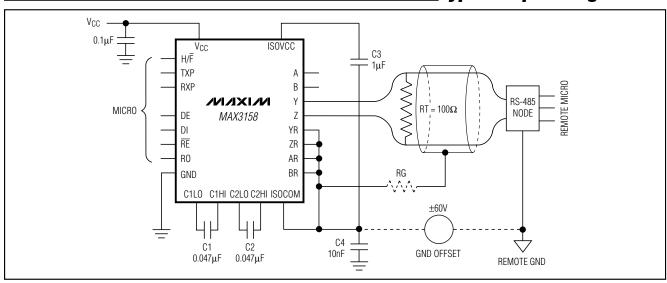
- ♦ ±60V Isolated Data Interface
- ♦ +5V Single Supply
- **♦ Low-Cost Replacement for Opto-Isolated Transceivers**
- **♦ True Fail-Safe Receiver While Maintaining** EIA/TIA-485 Compliance
- ♦ Pin-Selectable Full/Half-Duplex Operation
- ♦ Phase Controls to Correct for Twisted-Pair Reversal
- ♦ 25µA Low-Power Shutdown Mode
- ◆ Thermal Shutdown for Driver Overload Protection
- ♦ 28-Pin SSOP Package
- ♦ Slew-Rate-Limited Reduced EMI

### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX3158CAI	0°C to +70°C	28 SSOP
MAX3158CPI	0°C to +70°C	28 PDIP
MAX3158EAI	-40°C to +85°C	28 SSOP
MAX3158EPI	-40°C to +85°C	28 PDIP

Pin Configurations appear at end of data sheet.

## Typical Operating Circuit



MIXIM

Maxim Integrated Products 1

### **ABSOLUTE MAXIMUM RATINGS**

(All voltages referenced to GND, unless otherwise noted.)

	0	•
Supply '	Voltage (VCC)	+7V
		±75V
Isolated	Supply ISOVCC Relati	ive to Cable Ground
(ISOC	OM)	+7V
	nput, Output Voltage	
(DI, D	E, RE, TXP, RXP, RO)	0.3V to $(V_{CC} + 0.3V)$
Digital I	nputs $(H/\overline{F})$ Relative to	Cable Ground
(ISOC	OM)	0.3V to (ISOVCC + 0.3V)
Driver C	Output Voltage (Y, Z) Re	elative to Cable Ground
(ISOC	OM)	8V to +12.5V
	1 0 ( , ,	Relative to Cable Ground
		8V to +12.5V
	, ,	ZR, AR, BR) Relative to Cable
Groun	ıd (ISOCOM)	8V to +12.5V

Charge-Pump Capacitance Low	
(C1LO, C2LO)	0.3V to (V <sub>CC</sub> + 0.3V)
Charge-Pump Capacitance High (	C1HI, C2HI) Relative
to Cable Ground (ISOCOM)	0.3V to (ISOVCC + 0.3V)
Continuous Power Dissipation (TA	= +70°C)
28-Pin SSOP (derate 10.8mW/°C	
28-Pin PDIP (derate 14.3mW/°C	above +70°C)1143mW
Operating Temperature Ranges	
MAX3158C_I	0°C to +70°C
MAX3158E_I	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	
Lead Temperature (soldering, 10s	)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +5V \pm 5\%, Y_{R} = Z_{R} = A_{R} = B_{R} = ISOCOM, C_{1} = C_{2} = 0.047\mu F, C_{3} = C_{4} = 1\mu F, T_{A} = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $V_{CC} = +5V$  and  $T_{A} = +25^{\circ}C$ .) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DRIVER						
Differential Driver Output, No Load	V <sub>OD1</sub>	Figure 1, R = $10M\Omega$			6	V
Differential Driver Output,	V <sub>OD2</sub>	Figure 1, R = $50\Omega$ (RS-422)	2.0			V
Loaded	VOD2	Figure 1, R = $27\Omega$ (RS-485)	1.5			T *
Change in Magnitude of Differential Output Voltage (Note 2)	ΔV <sub>OD</sub>	Figure 1, R = $50\Omega$ or R = $27\Omega$			0.2	V
Driver Common-Mode Voltage	Voc	Figure 1, R = $50\Omega$ or R = $27\Omega$ , $V_{OC}$ relative to ISOCOM			3.5	V
Change in Magnitude of Common-Mode Voltage (Note 2)	ΔV <sub>OC</sub>	Figure 1, R = $50\Omega$ or R = $27\Omega$			0.2	V
Input High Voltage	VIH	DE, DI, RE, TXP, RXP, relative to GND, H/F relative to ISOCOM	2.0			V
Input Low Voltage	VIL	DE, DI, RE, TXP, RXP, relative to GND, H/F relative to ISOCOM			0.8	V
DI Input Hysteresis	V <sub>HYS</sub>			100		mV

## **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = +5V \pm 5\%, YR = ZR = AR = BR = ISOCOM, C1 = C2 = 0.047 \mu F, C3 = C4 = 1 \mu F, T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $V_{CC} = +5V$  and  $T_A = +25^{\circ}C$ .) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
la act Comment	I <sub>IN1</sub>	DE, DI, RE			±2	
Input Current	I <sub>IN2</sub>	H/F, TXP, RXP internal pulldown	10		40	μΑ
Input Current (A and D)	l	DE = GND, $V_{CC}$ = GND or 5.25V, -7V $\leq$ (V <sub>IN</sub> - V <sub>ISOCOM</sub> ) $\leq$ +12V, AR = BR = ISOCOM	-5.0		+8.0	
Input Current (A and B)	IIN3	DE = GND, $V_{CC}$ = GND or 5.25V, -7V $\leq$ (V <sub>IN</sub> - V <sub>ISOCOM</sub> ) $\leq$ +12V, AR open, BR open	-0.58		+1.0	mA
Output Leakage (Y and Z)	1-	DE = GND, $V_{CC}$ = GND or 5.25V, -7V $\leq$ (V <sub>IN</sub> - V <sub>ISOCOM</sub> ) $\leq$ +12V, YR = ZR = ISOCOM	-5.0		+8.0	
Full Duplex	IO	DE = GND, $V_{CC}$ = GND or 5.25V, -7V $\leq$ (V <sub>IN</sub> - V <sub>ISOCOM</sub> ) $\leq$ +12V, YR open, ZR open	-0.58		+1.0	mA mA
Driver Short-Circuit Output	losp1	VISOCOM - 7V ≤ VOUT ≤ VISOVCC	-250			m Λ
Current (Note 3)	los <sub>D2</sub>	VISOCOM - 7V ≤ VOUT ≤ VISOCOM + 12V			250	mA
RECEIVER						
Receiver Differential Threshold Voltage	V <sub>TH</sub>	-7V ≤ V <sub>CM</sub> - V <sub>ISOCOM</sub> ≤ +12V	-200	-125	-50	mV
Receiver Input Hysteresis	$\Delta V_{TH}$			25		mV
Receiver Output High Voltage	VoH	$I_O = -4mA$ , $V_{ID} = -50mV$	V <sub>CC</sub> - 1.5			V
Receiver Output Low Voltage	V <sub>OL</sub>	$I_O = 4mA$ , $V_{ID} = -200mV$			0.4	V
Three-State Output Current at Receiver	lozr	0.4V ≤ V <sub>O</sub> ≤ 2.4V			±1	μΑ
		-7V ≤ V <sub>CM</sub> - V <sub>ISOCOM</sub> ≤ +12V, AR = BR = ISOCOM	1.5			1.0
Receiver Input Resistance	R <sub>IN</sub>	-7V ≤ V <sub>CM</sub> - V <sub>ISOCOM</sub> ≤ +12V, AR open, BR open	12			kΩ
Receiver Output Short-Circuit Current	IOSR	OV ≤ V <sub>RO</sub> ≤ V <sub>CC</sub>	±7		±100	mA
SUPPLY CURRENT						
Supply Current	Icc	No load, $\overline{RE}$ = DE = DI = GND or V <sub>CC</sub>		25	85	mA
Supply Current in Shutdown	loupy	DE = GND, RE = VCC, VISOCOM = GND		25	60	
Mode	ISHDN	DE = GND, RE = VCC, VISOCOM = ±60V			±650	μA
Maximum Ground Differential	ΔV <sub>GND</sub>	DE = GND, RE = V <sub>CC</sub> , I ISOCOM leakage I ≤ 650μA	±60			V

### **SWITCHING CHARACTERISTICS**

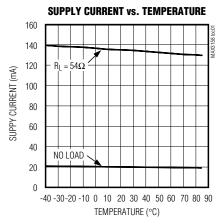
 $(V_{CC} = +5V \pm 5\%, YR = ZR = AR = BR = ISOCOM, C1 = C2 = 0.047 \mu F, C3 = C4 = 1 \mu F.$  Typical values are at  $V_{CC} = +5V$  and  $T_{A} = +25$ °C.)

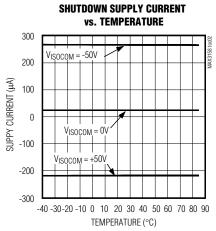
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Driver less to the Output	tDPLH	Figures 3 and 5, $R_{DIFF}$ = $54\Omega$ , $C_{L1}$ = $C_{L2}$ = $100pF$	400	1400	2000	
Driver Input to Output	tDPHL	Figures 3 and 5, $R_{DIFF}$ = $54\Omega$ , $C_{L1}$ = $C_{L2}$ = $100pF$	400	1400	2000	ns
Driver Output Skew   tDPLH - tDPHL	tDSKEW	Figures 3 and 5, $R_{DIFF}$ = $54\Omega$ , $C_{L1}$ = $C_{L2}$ = $100pF$			250	ns
Driver Rise or Fall Time	t <sub>DR</sub> , t <sub>DF</sub>	Figures 3 and 5, $R_{DIFF}$ = $54\Omega$ , $C_{L1}$ = $C_{L2}$ =100pF	200	1200	2200	ns
Maximum Data Rate	fMAX		250			kbps
Driver Enable to Output High	tDZH	Figures 4 and 6, C <sub>L</sub> = 100pF, S2 closed			3500	ns
Driver Enable to Output Low	t <sub>DZL</sub>	Figures 4 and 6, C <sub>L</sub> = 100pF, S1 closed			3500	ns
Driver Disable Time from Low	tDLZ	Figures 4 and 6, C <sub>L</sub> = 15pF, S1 closed			300	ns
Driver Disable Time from High	tDHZ	Figures 4 and 6, C <sub>L</sub> = 15pF, S2 closed			300	ns
Receiver Input to Output	tRPLH, tRPHL	Figures 7 and 9;   V <sub>ID</sub>   ≥ 2.0V		440	600	ns
Differential Receiver Skew   tRPLH - tRPHL	trskew	Figures 7 and 9;   V <sub>ID</sub>   ≥ 2.0V		20		ns
Receiver Enable to Output Low	trzl	Figures 2 and 8, C <sub>L</sub> = 100pF, S1 closed		20	50	ns
Receiver Enable to Output High	trzh	Figures 2 and 8, C <sub>L</sub> = 100pF, S2 closed		20	50	ns
Receiver Disable Time from Low	t <sub>RLZ</sub>	Figures 2 and 8, C <sub>L</sub> = 100pF, S1 closed		200	500	ns
Receiver Disable Time from High	tRHZ	Figures 2 and 8, C <sub>L</sub> = 100pF, S2 closed		200	500	ns
Time to Shutdown	tshdn	(Note 4)	50	200	700	ns
Driver Enable from Shutdown to Output High	t <sub>DZH</sub> (SHDN)	Figures 4 and 6, C <sub>L</sub> = 15pF, S2 closed		0.2	1	ms
Driver Enable from Shutdown to Output Low	t <sub>DZL</sub> (SHDN)	Figures 4 and 6, C <sub>L</sub> = 15pF, S1 closed		0.2	1	ms
Receiver Enable from Shutdown to Output High	t <sub>RZH</sub> (SHDN)	Figures 2 and 8, C <sub>L</sub> = 100pF, S2 closed		0.2	1	ms
Receiver Enable from Shutdown to Output Low	t <sub>RZL</sub> (SHDN)	Figures 2 and 8, C <sub>L</sub> = 100pF, S1 closed		0.2	1	ms
Charge-Pump Oscillating Frequency	fosc			1.3		MHz

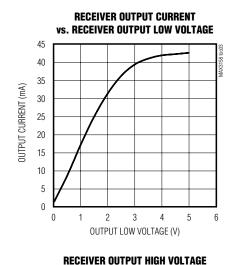
- **Note 1:** All currents into the device are positive; all currents out of the device are negative. All voltages are referred to device ground unless otherwise noted.
- Note 2:  $\Delta V_{OD}$  and  $\Delta V_{OC}$  are the changes in  $V_{OD}$  and  $V_{OC}$ , respectively, when the DI input changes state.
- Note 3: Current level applies to peak current just prior to foldback-current limiting.
- Note 4: The device is put into shutdown by bringing  $\overline{\text{RE}}$  high and DE low. If the enable inputs are in this state for less than 50ns, the device is guaranteed not to enter shutdown. If the enable inputs are in this state for at least 700ns, the device is guaranteed to have entered shutdown.

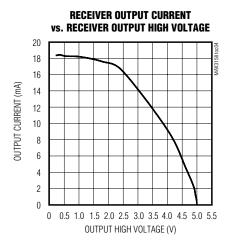
### **Typical Operating Characteristics**

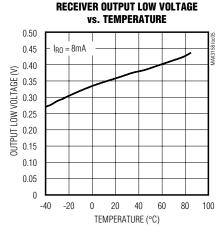
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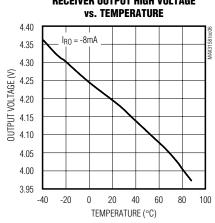


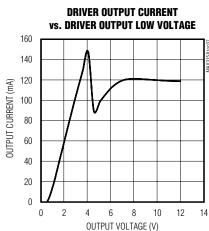


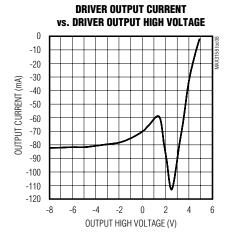


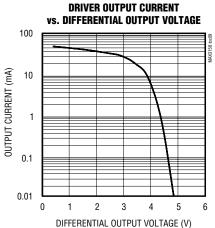






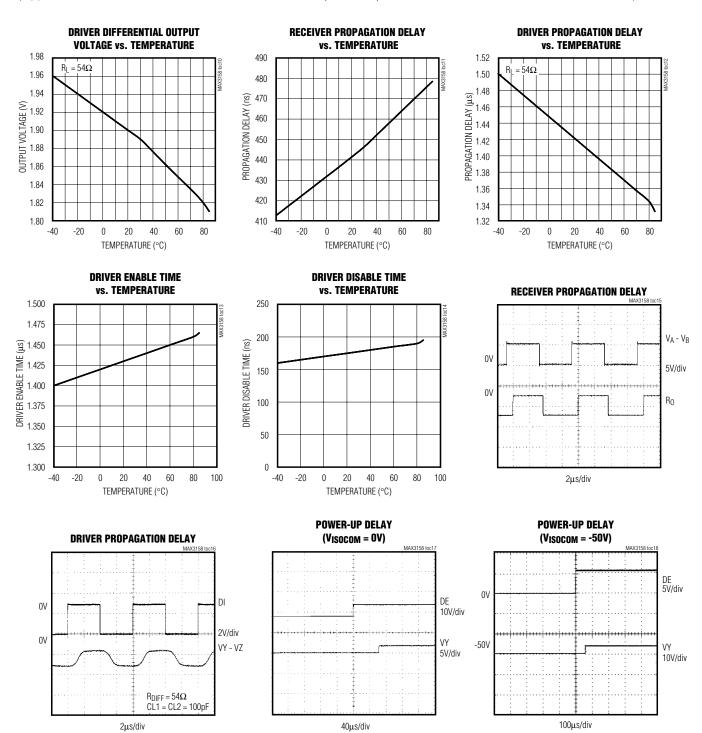






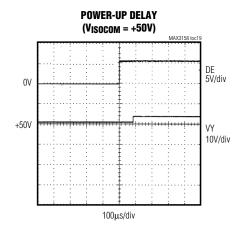
## **Typical Operating Characteristics (continued)**

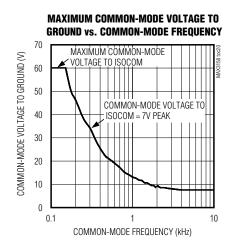
 $(V_{CC} = +5V, YR = ZR = AR = BR = ISOCOM, C1 = C2 = 0.047 \mu F, C3 = 1 \mu F, C4 = 10 n F, T_A = +25 ^{\circ}C, unless otherwise noted.)$ 



## **Typical Operating Characteristics (continued)**

 $(V_{CC} = +5V, YR = ZR = AR = BR = ISOCOM, C1 = C2 = 0.047 \mu F, C3 = 1 \mu F, C4 = 10 n F, T_A = +25 ^{\circ}C, unless otherwise noted.)$ 





## **Test Circuits and Timing Diagrams**

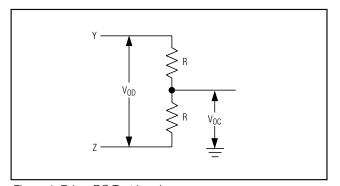


Figure 1. Driver DC Test Load

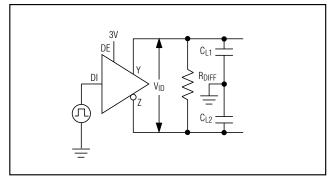


Figure 3. Driver Timing Test Circuit

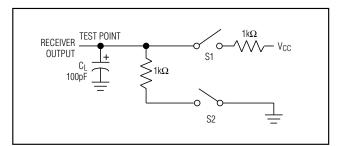


Figure 2. Receiver Enable/Disable Timing Test Load

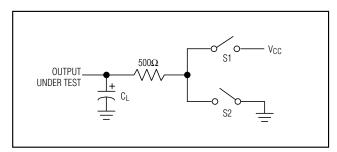


Figure 4. Driver Enable/Disable Timing Test Load

## **Test Circuits and Timing Diagrams (continued)**

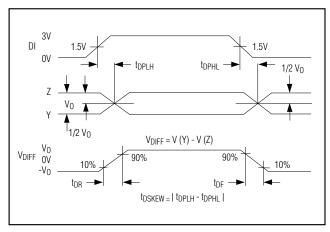


Figure 5. Driver Propagation Delays

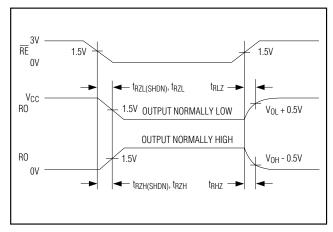


Figure 8. Receiver Enable and Disable Times

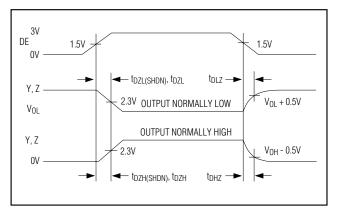


Figure 6. Driver Enable and Disable Times

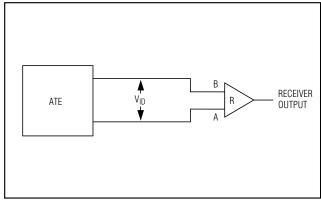


Figure 9. Receiver Propagation Delay Test Circuit

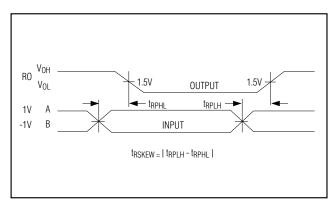


Figure 7. Receiver Propagation Delays

## \_Pin Description

1 2 3 4 5 6, 7,	PDIP  2  3  4  5  6  1, 12, 14, 15, 28  7  8	RO RE DE DI C1LO N.C.	FUNCTION  Receiver Output. When RE is low and A - B > -50mV, RO will be high; if A - B ≤ -200mV, RO will be low.  Receiver Output Enable. Drive RE low to enable RO.  Driver Output Enable. Drive DE high to enable driver outputs.  Driver Input. With DE high, a low on DI forces the noninverting output low and the inverting output high; with DI high, outputs reverse.  Connect to the negative terminal of C1 (0.047μF, 100V).  No Connection. Not internally connected.
2 3 4 5 6, 7, 12, 22, 23	3 4 5 6 1, 12, 14, 15, 28 7	RE DE DI C1LO N.C.	RO will be low.  Receiver Output Enable. Drive RE low to enable RO.  Driver Output Enable. Drive DE high to enable driver outputs.  Driver Input. With DE high, a low on DI forces the noninverting output low and the inverting output high; with DI high, outputs reverse.  Connect to the negative terminal of C1 (0.047µF, 100V).  No Connection. Not internally connected.
3 4 5 6, 7, 12, 22, 23	4 5 6 1, 12, 14, 15, 28 7	DE DI C1LO N.C.	Driver Output Enable. Drive DE high to enable driver outputs.  Driver Input. With DE high, a low on DI forces the noninverting output low and the inverting output high; with DI high, outputs reverse.  Connect to the negative terminal of C1 (0.047µF, 100V).  No Connection. Not internally connected.
4 5 6, 7, 12, 22, 23	5 6 1, 12, 14, 15, 28 7	DI C1LO N.C.	Driver Input. With DE high, a low on DI forces the noninverting output low and the inverting output high; with DI high, outputs reverse.  Connect to the negative terminal of C1 (0.047µF, 100V).  No Connection. Not internally connected.
5 6, 7, 12, 22, 23	6 1, 12, 14, 15, 28 7	C1LO N.C.	output high; with DI high, outputs reverse.  Connect to the negative terminal of C1 (0.047µF, 100V).  No Connection. Not internally connected.
6, 7, 12, 22, 23	1, 12, 14, 15, 28	N.C.	No Connection. Not internally connected.
12, 22,	14, 15, 28 7		,
8		C1HI	0
	8		Connect to the positive terminal of C1 (0.047µF, 100V).
9		ISOVCC	Internally generated power-supply voltage, referenced to the cable ground (ISOCOM). Connect a 1µF capacitor to ISOCOM.
10	9	H/F	Half/Full-Duplex Selector Pin. Leave open, or connect to ISOCOM to select Full Duplex, or connect to ISOVCC to select Half Duplex.
11	10	ZR	Connect to ISOCOM for a 1.5k $\Omega$ input impedance on Z. Leave open for a 12k $\Omega$ input impedance on Z.
13	11	YR	Connect to ISOCOM for a 1.5k $\Omega$ input impedance on Y. Leave open for a 12k $\Omega$ input impedance on Y.
14	13	ISOCOM	Cable Ground
15	16	Z	Inverting Driver Output (and Inverting Receiver Input in Half-Duplex Mode)
16	17	Υ	Noninverting Driver Output (and Noninverting Receiver Input in Half-Duplex Mode)
17	18	В	Inverting Receiver Input in Full-Duplex Mode
18	19	Α	Noninverting Receiver Input in Full-Duplex Mode
19	20	BR	Connect to ISOCOM for a 1.5k $\Omega$ input impedance on B. Leave open for a 12k $\Omega$ input impedance on B.
20	21	AR	Connect to ISOCOM for a $1.5k\Omega$ input impedance on A. Leave open for a $12k\Omega$ input impedance on A.
21	22	C2HI	Connect to the positive terminal of C2 (0.047µF, 100V).
24	23	C2LO	Connect to the negative terminal of C2 (0.047µF, 100V).
25	24	GND	Ground
26	25	TXP	Transmitter Phase. Leave open, or connect to GND for normal transmitter polarity, or connect to $V_{\rm CC}$ to invert the transmitter polarity.
27	26	RXP	Receiver Phase. Leave open, or connect to GND for normal receiver polarity, or connect to V <sub>CC</sub> to invert the receiver polarity.
28	27	Vcc	+4.75V to +5.25V Positive Supply. Connect a 0.1µF capacitor to GND.



### **Detailed Description**

The MAX3158 is a high CMRR RS-485/RS-422 data-communications interface providing  $\pm 60V$  isolation in a hybrid microcircuit. A single  $\pm 5V$  supply on the logic side powers both sides of the interface, with external 100V capacitors transferring power from the logic side to the isolated side (see *Block Diagram*). The MAX3158 typically draws 25mA of supply current when unloaded or when fully loaded with the driver disabled. Supply current drops to  $25\mu A$  when the device is placed in shutdown mode (see *Low-Power Shutdown Mode* section). The MAX3158 transceiver for RS-485/RS-422 communication contains one driver and one receiver.

This device features fail-safe circuitry, which guarantees a logic-high receiver output when the receiver inputs are open or shorted, or when they are connected to a terminated transmission line with all drivers disabled (see *Fail-Safe* section). The MAX3158 is selectable between half- and full-duplex communication by connecting a selector pin to ISOVCC or ISOCOM, respectively. Drivers are output short-circuit current limited. Thermal shutdown circuitry protects drivers against excessive power dissipation. When activated, the thermal shutdown circuitry places the driver outputs into a high-impedance state. The device also features independently programmable receiver and transmitter output phase through separate pins. The MAX3158 is a low-cost replacement for opto-isolated transceivers.

#### Fail-Safe

The MAX3158 **guarantees** a logic-high receiver output when the receiver inputs are shorted or open, or when they are connected to a terminated transmission line with all drivers disabled. The receiver threshold is fixed between -50mV and -200mV. If the differential receiver input voltage (A - B) is greater than or equal to -50mV, RO is logic high. If A - B is less than or equal to -200mV, RO is logic low. In the case of a terminated bus with all transmitters disabled, the receiver's differential input voltage is pulled to 0V by the termination. With the receiver thresholds of the MAX3158, this results in a logic high with a 50mV minimum noise margin. Unlike competitor's fail-safe devices, the -50mV to -200mV threshold complies with the ±200mV EIA/TIA-485 standard.

### **MAX3158 Programming**

The MAX3158 has several programmable operating modes. Occasionally, twisted-pair lines are reversed. The MAX3158 has two pins that invert the phase of the driver and the receiver to correct for this problem. For normal operation, drive TXP and RXP low, connect them to ground, or leave them unconnected (internal pulldown). To invert the driver phase, drive TXP high or

connect it to V<sub>CC</sub>. To invert the receiver phase, drive RXP high or connect it to V<sub>CC</sub>. Note that the receiver threshold is positive when RXP is high.

The MAX3158 can operate in full- or half-duplex mode. Connect H/ $\overline{F}$  to ISOCOM for full-duplex mode, and connect it to ISOVCC for half-duplex operation. In half-duplex mode, the receiver inputs are switched to the driver outputs, connecting outputs Y and Z to inputs A and B, respectively. In half-duplex mode, the internal full-duplex receiver input resistors are still connected to pins A and B.

#### **Low-Power Shutdown Mode**

The low-power shutdown mode is initiated by bringing both RE high and DE low. In shutdown, this device typically draws only 25µA of supply current, and no power is transferred across the isolation capacitors in this mode. RE and DE may be driven simultaneously; the parts are guaranteed not to enter shutdown if RE is high and DE is low for less than 50ns. If the inputs are in this state for at least 700ns, the parts are guaranteed to enter shutdown. Enable times t\_ZH and t\_ZL in the Switching Characteristics table assume the part was not in a low-power shutdown state. Enable times t\_zh(SHDN) and t\_zl(SHDN) assume the parts were shut down. It takes drivers and receivers longer to become enabled from low-power shutdown mode t\_ZH(SHDN), t\_ZL(SHDN) than from driver/receiver-disable mode  $(t_ZH, t_ZL).$ 

### **Driver Output Protection**

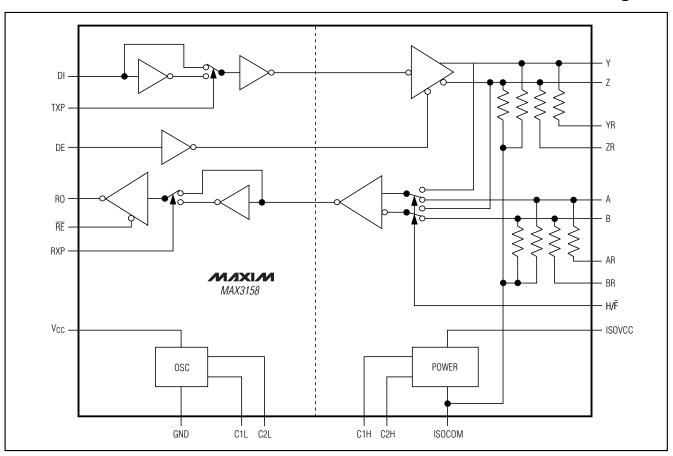
Two mechanisms prevent excessive output current and power dissipation caused by faults or by bus contention. The first, a foldback current limit on the output stage, provides immediate protection against short circuits over the whole common-mode voltage range (see *Typical Operating Characteristics*). The second, a thermal shutdown circuit, forces the driver outputs into a high-impedance state if the die temperature becomes excessive—typically around +150°C.

### Applications Information

#### Capacitor and Grounding Resistor Selection

The value for the charge-pump capacitors C1 and C2 should be between 47nF and 100nF. Smaller values will result in insufficient supply voltage on the isolated side. Larger values are allowed but will not result in better charge-pump capacity. The values for C1 and C2, as well as that of C4, determine the maximum frequency and amplitude of the voltage difference (under operating conditions) between the local and isolated ground. Besides the capacitor values, this maximum frequency

### **Block Diagram**



and amplitude are also determined by the resistance between the remote ground and the ISOCOM pin. The receiver input resistors will cause the isolated common voltage to go to the mean voltage of the receiver inputs, which will be a direct function of the remote ground potential. The receiver input resistance and the capacitors C1, C2, and C4 set up a time constant that limits how fast the ISOCOM pin can follow variations in the remote ground voltage. Connecting YR and ZR in halfduplex operation, or AR and BR in full-duplex operation, to ISOCOM results in a relatively low input impedance of the MAX3158 receiver inputs ( $2k\Omega$ ). This allows for a 60Hz sine wave with a 60V maximum amplitude (see Typical Operating Characteristics). If YR, ZR, AR, and BR are left open, the receiver input impedance is  $12k\Omega$ allowing up to 32 transceivers on the bus. To guarantee the same low time constant under those conditions, use a shielded cable with a  $1k\Omega$  resistor connected between

the shield and ISOCOM. Using a lower value for this resistor is not recommended because this could trigger a holding current in the internal ESD protection device if the ±75V isolation limit is exceeded.

A single point hard-ground connection for the shield is recommended.

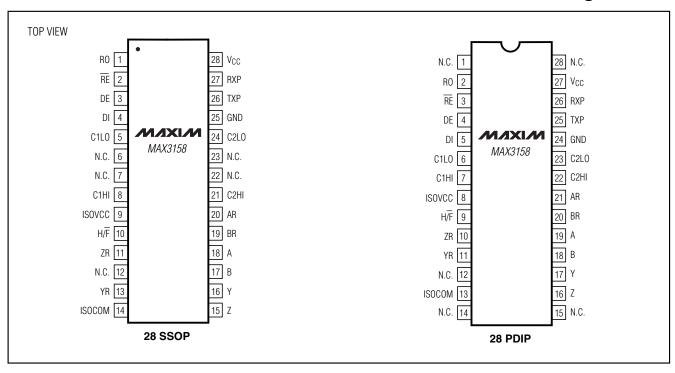
### Communication Between Two MAX3158s

If two MAX3158 devices are used to communicate with each other, one of the devices must have ISOCOM connected to local ground. Failure to do so will result in floating ISOCOM pins, with both devices trying to adapt to the isolated ground of the other.

Chip Information

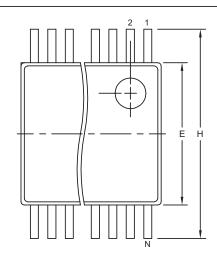
**TRANSISTOR COUNT: 1309** 

## Pin Configurations



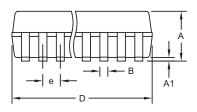
## **Package Information**

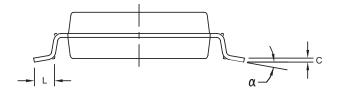
(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



	INCH	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.068	0.078	1.73	1.99
A1	0.002	0.008	0.05	0.21
В	0.010	0.015	0.25	0.38
С	0.004 0.0		0.09	0.20
D	S	EE VARI	ATIONS	
Е	0.205	0.212	5.20	5.38
е	0.0256 BSC		0.65	BSC
Н	0.301	0.311	7.65	7.90
L	0.025	0.037	0.63	0.95
α	0∞	8∞	0∞	8∞

	INC	HES	MILLIM	ETERS		
	MIN MAX		MIN	MAX	N	
D	0.239	0.249	6.07	6.33	14L	
D	0.239	0.249	6.07	6.33	16L	
D	0.278	0.289	7.07	7.33	20L	
D	0.317	0.328	8.07	8.33	24L	
D	0.397	0.407	10.07	10.33	28L	





#### NOTES:

- 1. D&E DO NOT INCLUDE MOLD FLASH.
- 2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED .15 MM (.006").
- 3. CONTROLLING DIMENSION: MILLIMETERS.
- 4. MEETS JEDEC MO150.
- 5. LEADS TO BE COPLANAR WITHIN 0.10 MM.

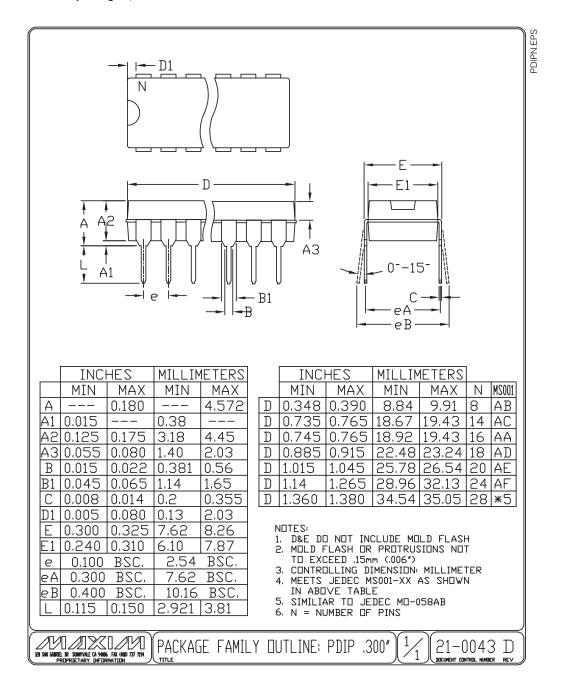


PACKAGE OUTLINE, SSOP, 5.3 MM

PROVAL DOCUMENT CONTROL NO. 21-0056

### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



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